

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s) : Dusberg et al.
Serial No. : 10/573,862
Filed : October 24, 2006
For : Heat-Conducting Packaging of Electronic Circuit Units
Group Art Unit : 2815
Confirmation No. : 7026
Examiner : Chris C. Chu

Mail Stop: Amendments
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

STATEMENT UNDER 37 CFR 3.73(b)

Infineon Technologies AG hereby states that it is the assignee of the entire right, title, and interest of the above-identified application. The assignment of the above-identified application from the Inventors to Infineon Technologies AG was recorded on June 7, 2006 and assigned Reel/Frame No. 017753/0136.

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

Respectfully submitted,

By: 
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Dated: October 6, 2008

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